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TOPPAN Inc. Signs a Sales Partner Agreement with Spring Semiconductor Sdn. Bhd. in Malaysia — Based on this agreement, TOPPAN Technical Design Center Inc. to enhance the sales structure in Malaysia and the APAC region.

TOPPAN

TOPPAN Technical Design Center Inc.

SPRING SEMI

TOPPAN Inc., the parent company of TOPPAN Technical Design Center Inc. (“TDC”), has entered into an agreement with Spring Semiconductor Sdn. Bhd. (“Spring Semiconductor”), a leading provider of semiconductor design and prototyping solutions in Malaysia, under which Spring Semiconductor will act as a sales partner for IC design services, MPW¹, and ASIC² turnkey³ services in Malaysia and other APAC regions. This strategic partnership will strengthen TDC’s service delivery capabilities in those countries and regions.

In recent years, Malaysia has seen an acceleration in semiconductor industry activity, particularly in Penang State, which is often referred to as the “Silicon Valley of the East,” and the region is becoming increasingly important as a hub for semiconductor manufacturing and design in Southeast Asia.

In Malaysia, home to one of the world’s leading semiconductor clusters, we have established a system to deliver TDC’s Japanese-quality design expertise and global manufacturing network—cultivated over many years—in a manner tailored to local market demands by partnering with Spring Semiconductor, a company with deep knowledge of local business practices and technical needs.

The ability to directly leverage TDC's specialized expertise and manufacturing network offers significant advantages for local design houses, startups, and academic institutions conducting cutting-edge research, which often face resource constraints. Combining the strengths of both companies will remove technical barriers from the prototyping stage through to mass production, thereby contributing significantly to powering a next-generation semiconductor ecosystem based in Malaysia and enhancing the industrial competitiveness of the region as a whole.

Under the agreement, Spring Semiconductor will assume the following roles:

- **Expanding service sales in Malaysia and the APAC region:** Expanding sales of design support, MPW, turnkey solutions, and other services provided by TDC
- **Local support :** Providing on-site support, training, and customer engagement to accelerate technology adoption
- **Outreach to Malaysia's industries :** Driving industry engagement to enhance Malaysia's roles in its regional semiconductor design and manufacturing

Ken Khoo, CEO of Spring Semiconductor, stated: "We are honored to partner with TDC. Through this collaboration, we will bring world-class capabilities to the rapidly growing semiconductor sector in Malaysia, lower barriers to innovation, and foster a thriving ecosystem where designers and manufacturers can grow together."

Kazushige Koshika, President and CEO of TOPPAN Technical Design Center, stated: "TDC is committed to realizing semiconductor innovation in Southeast Asia. Our partnership with Spring Semiconductor, a highly trusted technology leader in Malaysia, aligns with our mission to provide high-quality semiconductor design and manufacturing management services. Through this partnership, we aim to contribute to the development of the semiconductor ecosystem in Southeast Asia."

As a solid bridge between design and manufacturing, TDC and Spring Semiconductor will support the further advancement of the semiconductor ecosystem in Malaysia and provide strong backing for the next generation of technological innovations originating in Asia and reaching the world.

About Spring Semiconductor Sdn. Bhd.

Spring Semiconductor is a technology company that supports semiconductor design and prototyping for corporations, startups, and academia. Through design services, training, and ecosystem development, we aim to bring innovative ideas to market faster, smarter, and more cost-effectively.

<https://springsem.com/>

About TOPPAN Technical Design Center Inc.

TOPPAN Technical Design Center is a global leader in semiconductor services, providing design support, turnkey solutions, MPW access, and advanced packaging solutions to customers worldwide. Leveraging our expertise as a bridge between design and manufacturing, we support our customers' business growth from concept stage through to mass production.

<https://www.toptdc.toppan.com/en/>

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¹ MPW (Multi-Project Wafer): A manufacturing method where multiple different designs (projects) share a single silicon wafer, significantly reducing prototyping costs.

² ASIC: An integrated circuit (IC) designed and manufactured specifically for a particular device or application. Compared to general-purpose ICs, ASICs offer superior processing speeds, smaller footprints, reduced power consumption, and the ability to protect proprietary technology through hardware-level security.

³ Turnkey service: Where all stages (from initial specification and design to manufacturing, packaging, testing, and final delivery) are handled collectively based on the customer's requirements. The term originates from the metaphor of a system being delivered in a state where the user only needs to 'turn the key' to start using it.